



BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm
Board overall dimensions: 30.1000 mm x 35.1000 mm
Min track/spacing: 0.1524 mm / 0.1524 mm Min hole diameter: 0.2540 mm
Copper Finish: None Impedance Control: No
Castellated pads: No Plated Board Edge: No
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

HugonLabs

Sheet:
File: besse_lfilter.kicad_pcb

Title: Bessel Filter

Size: USLetter	Date: 2022-03-13	Rev: 1.0
KiCad E.D.A.	kicad 6.0.2-378541a8eb-116-ubuntu20.04.1	Id: 1/1